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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Coldfire V2
Core Size	32-Bit Single-Core
Speed	60MHz
Connectivity	Ethernet, I²C, SPI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	80
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	121-LBGA
Supplier Device Package	121-MAPBGA (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcf52233cvm60j

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1 MCF52235 Family Configurations

Table 1. MCF52235 Family Configurations

Module	52230	52231	52232	52233	52234	52235	52236
Version 2 ColdFire Core with EMAC (Enhanced Multiply-Accumulate Unit)	•	•	•	•	•	•	•
System Clock (MHz)	60	60	50	60	60	60	50
Performance (Dhrystone 2.1 MIPS)	56	56	46	56	56	56	46
Flash / Static RAM (SRAM)	128/32 Kbytes	128/32 Kbytes	128/32 Kbytes	256/32 Kbytes	256/32 Kbytes	256/32 Kbytes	256/32 Kbytes
Interrupt Controllers (INTC0/INTC1)	•	•	•	•	•	•	•
Fast Analog-to-Digital Converter (ADC)	•	•	•	•	•	•	•
Random Number Generator and Crypto Acceleration Unit (CAU)	—	—	—	—	—	•	—
FlexCAN 2.0B Module	—	•	—	—	•	•	—
Fast Ethernet Controller (FEC) with on-chip interface (EPHY)	•	•	•	•	•	•	•
Four-channel Direct-Memory Access (DMA)	•	•	•	•	•	•	•
Software Watchdog Timer (WDT)	•	•	•	•	•	•	•
Programmable Interrupt Timer	2	2	2	2	2	2	2
Four-Channel General Purpose Timer	•	•	•	•	•	•	•
32-bit DMA Timers	4	4	4	4	4	4	4
QSPI	•	•	•	•	•	•	•
UART(s)	3	3	3	3	3	3	3
I^2C	•	•	•	•	•	•	•
Eight/Four-channel 8/16-bit PWM Timer	•	•	•	•	•	•	•
General Purpose I/O Module (GPIO)	•	•	•	•	•	•	•
Chip Configuration and Reset Controller Module	•	•	•	•	•	•	•
Background Debug Mode (BDM)	•	•	•	•	•	•	•
JTAG - IEEE 1149.1 Test Access Port[1]	•	•	•	•	•	•	•
Package	80 LQFP 112 LQFP	80 LQFP 112 LQFP	80 LQFP	80 LQFP 112 LQFP	112 LQFP 121 MAPBGA	112 LQFP 121 MAPBGA	80 LQFP

[1] The full debug/trace interface is available only on the 112- and 121-pin packages. A reduced debug interface is bonded on the 80-pin package.

module is physically connected to the processor's high-speed local bus, it can quickly service core-initiated accesses or memory-referencing commands from the debug module.

The SRAM module is also accessible by the DMA. The dual-ported nature of the SRAM makes it ideal for implementing applications with double-buffer schemes, where the processor and a DMA device operate in alternate regions of the SRAM to maximize system performance.

1.2.5.2 Flash

The ColdFire flash module (CFM) is a non-volatile memory (NVM) module that connects to the processor’s high-speed local bus. The CFM is constructed with four banks of 32 K×16-bit flash arrays to generate 256 Kbytes of 32-bit flash memory. These arrays serve as electrically erasable and programmable, non-volatile program and data memory. The flash memory is ideal for program and data storage for single-chip applications, allowing for field reprogramming without requiring an external high voltage source. The CFM interfaces to the ColdFire core through an optimized read-only memory controller which supports interleaved accesses from the 2-cycle flash arrays. A backdoor mapping of the flash memory is used for all program, erase, and verify operations, as well as providing a read datapath for the DMA. Flash memory may also be programmed via the EzPort, which is a serial flash programming interface that allows the flash to be read, erased and programmed by an external controller in a format compatible with most SPI bus flash memory chips. This allows easy device programming via Automated Test Equipment or bulk programming tools.

1.2.6 Cryptography Acceleration Unit

The MCF52235 device incorporates two hardware accelerators for cryptographic functions. First, the CAU is a coprocessor tightly-coupled to the V2 ColdFire core that implements a set of specialized operations to increase the throughput of software-based encryption and message digest functions, specifically the DES, 3DES, AES, MD5 and SHA-1 algorithms. Second, a random number generator provides FIPS-140 compliant 32-bit values to security processing routines. Both modules supply critical acceleration to software-based cryptographic algorithms at a minimal hardware cost.

1.2.7 Power Management

The MCF52235 incorporates several low-power modes of operation which are entered under program control and exited by several external trigger events. An integrated power-on reset (POR) circuit monitors the input supply and forces an MCU reset as the supply voltage rises. The low voltage detector (LVD) monitors the supply voltage and is configurable to force a reset or interrupt condition if it falls below the LVD trip point.

1.2.8 FlexCAN

The FlexCAN module is a communication controller implementing version 2.0 of the CAN protocol parts A and B. The CAN protocol can be used as an industrial control serial data bus, meeting the specific requirements of reliable operation in a harsh EMI environment with high bandwidth. This instantiation of FlexCAN has 16 message buffers.

1.2.9 UARTs

The MCF52235 has three full-duplex UARTs that function independently. The three UARTs can be clocked by the system bus clock, eliminating the need for an external clock source. On smaller packages, the third UART is multiplexed with other digital I/O functions.

1.2.10 I²C Bus

The I²C bus is a two-wire, bidirectional serial bus that provides a simple, efficient method of data exchange and minimizes the interconnection between devices. This bus is suitable for applications requiring occasional communications over a short distance between many devices on a circuit board.

1.2.11 QSPI

The queued serial peripheral interface (QSPI) provides a synchronous serial peripheral interface with queued transfer capability. It allows up to 16 transfers to be queued at once, minimizing the need for CPU intervention between transfers.

1.2.12 Fast ADC

The Fast ADC consists of an eight-channel input select multiplexer and two independent sample and hold (S/H) circuits feeding separate 10- or 12-bit ADCs. The two separate converters store their results in accessible buffers for further processing.

The ADC can be configured to perform a single scan and halt, perform a scan whenever triggered, or perform a programmed scan sequence repeatedly until manually stopped.

The ADC can be configured for sequential or simultaneous conversion. When configured for sequential conversions, up to eight channels can be sampled and stored in any order specified by the channel list register. Both ADCs may be required during a scan, depending on the inputs to be sampled.

During a simultaneous conversion, both S/H circuits are used to capture two different channels at the same time. This configuration requires that a single channel may not be sampled by both S/H circuits simultaneously.

Optional interrupts can be generated at the end of the scan sequence if a channel is out of range (measures below the low threshold limit or above the high threshold limit set in the limit registers) or at several different zero crossing conditions.

1.2.13 DMA Timers (DTIM0–DTIM3)

There are four independent, DMA transfer capable 32-bit timers (DTIM0, DTIM1, DTIM2, and DTIM3) on the each device. Each module incorporates a 32-bit timer with a separate register set for configuration and control. The timers can be configured to operate from the system clock or from an external clock source using one of the DTINx signals. If the system clock is selected, it can be divided by 16 or 1. The input clock is further divided by a user-programmable 8-bit prescaler which clocks the actual timer counter register (TCRn). Each of these timers can be configured for input capture or reference (output) compare mode. Timer events may optionally cause interrupt requests or DMA transfers.

1.2.14 General Purpose Timer (GPT)

The general purpose timer (GPT) is a 4-channel timer module consisting of a 16-bit programmable counter driven by a 7-stage programmable prescaler. Each of the four channels can be configured for input capture or output compare. Additionally, one of the channels, channel 3, can be configured as a pulse accumulator.

A timer overflow function allows software to extend the timing capability of the system beyond the 16-bit range of the counter. The input capture and output compare functions allow simultaneous input waveform measurements and output waveform generation. The input capture function can capture the time of a selected transition edge. The output compare function can generate output waveforms and timer software delays. The 16-bit pulse accumulator can operate as a simple event counter or a gated time accumulator.

1.2.15 Periodic Interrupt Timers (PIT0 and PIT1)

The two periodic interrupt timers (PIT0 and PIT1) are 16-bit timers that provide interrupts at regular intervals with minimal processor intervention. Each timer can count down from the value written in its PIT modulus register or can be a free-running down-counter.

1.2.16 Pulse Width Modulation (PWM) Timers

The MCF52235 has an 8-channel, 8-bit PWM timer. Each channel has a programmable period and duty cycle as well as a dedicated counter. Each of the modulators can create independent continuous waveforms with software-selectable duty rates from 0 to 100%. The PWM outputs have programmable polarity and can be programmed as left-aligned outputs or center-aligned outputs. For higher period and duty cycle resolution, each pair of adjacent channels ([7:6], [5:4], [3:2], and [1:0]) can be concatenated to form a single 16-bit channel. The module can, therefore, be configured to support 8/0, 6/1, 4/2, 2/3, or 0/4 8-/16-bit channels.

1.2.17 Software Watchdog Timer

The watchdog timer is a 32-bit timer that facilitates recovery from runaway code. The watchdog counter is a free-running down-counter that generates a reset on underflow. To prevent a reset, software must periodically restart the countdown.

1.2.18 Phase Locked Loop (PLL)

The clock module contains a crystal oscillator, 8 MHz on-chip relaxation oscillator (OCO), phase-locked loop (PLL), reduced frequency divider (RFD), low-power divider status/control registers, and control logic. To improve noise immunity, the PLL, crystal oscillator, and relaxation oscillator have their own power supply inputs: VDDPLL and VSSPLL. All other circuits are powered by the normal supply pins, VDD and VSS.

1.2.19 Interrupt Controller (INTC0/INTC1)

There are two interrupt controllers on the MCF52235. These interrupt controllers are organized as seven levels with up to nine interrupt sources per level. Each interrupt source has a unique interrupt vector, and provide each peripheral with all necessary interrupts. Each internal interrupt has a programmable level [1-7] and priority within the level. The seven external interrupts have fixed levels/priorities.

1.2.20 DMA Controller

The direct memory access (DMA) controller provides an efficient way to move blocks of data with minimal processor intervention. It has four channels that allow byte, word, longword, or 16-byte burst line transfers. These transfers are triggered by software explicitly setting a DCRn[START] bit or by the occurrence of certain UART or DMA timer events.

1.2.21 Reset

The reset controller determines the source of reset, asserts the appropriate reset signals to the system, and keeps track of what caused the last reset. There are seven sources of reset:

- External reset input
- Power-on reset (POR)
- Watchdog timer
- Phase locked-loop (PLL) loss of lock
- PLL loss of clock
- Software

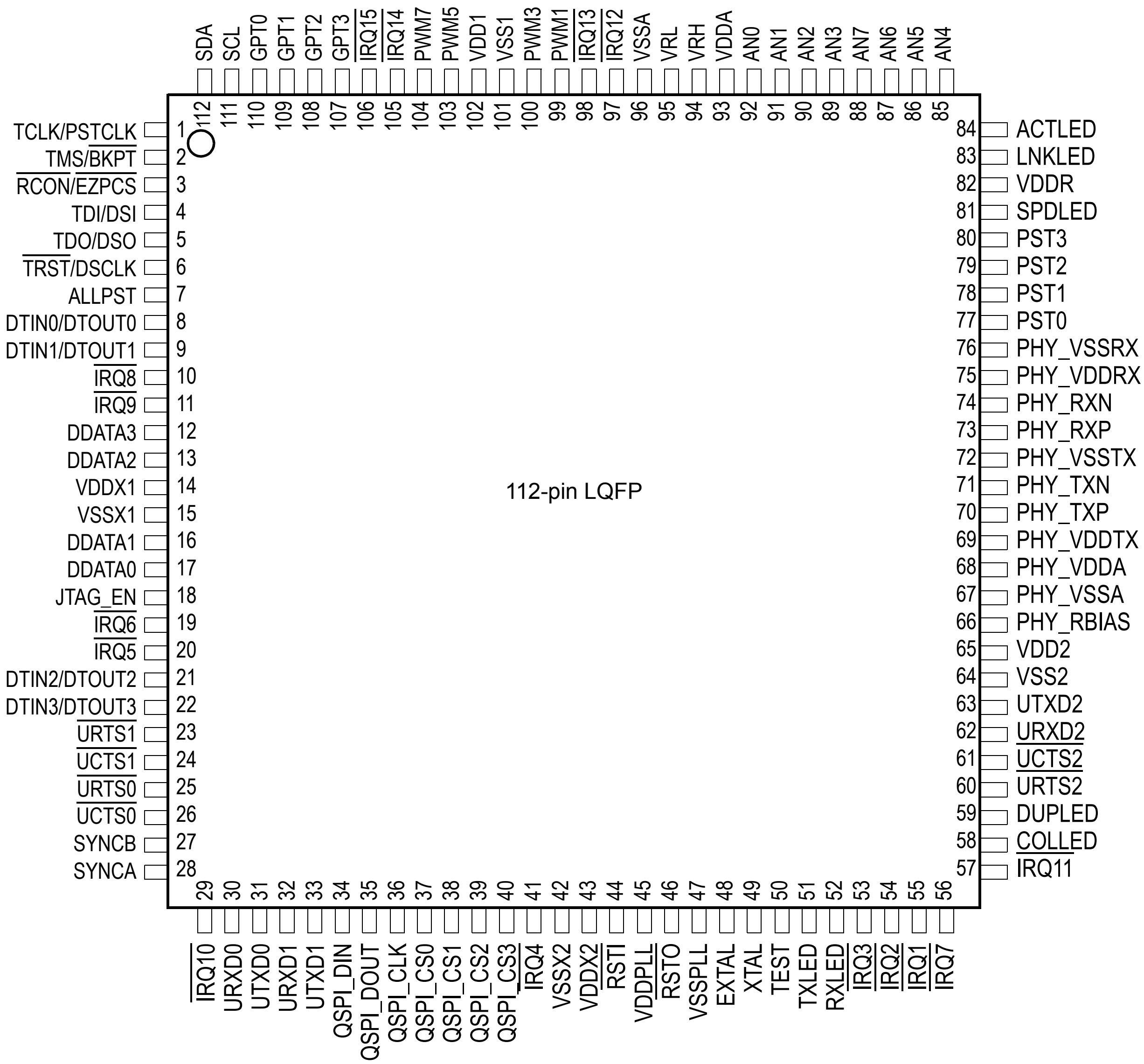


Figure 3. 112-pin LQFP Pin Assignments

Figure 4 shows the pinout configuration for the 121 MAPBGA.

	1	2	3	4	5	6	7	8	9	10	11
A	TCLK	SDA	SCL	$\overline{\text{IRQ15}}$	$\overline{\text{IRQ14}}$	$\overline{\text{IRQ13}}$	VSSA	VDDA	AN1	AN7	AN5
B	TMS	$\overline{\text{RCON}}$	GPT0	GPT3	PWM5	PWM1	VRL	VRH	AN2	AN6	AN4
C	$\overline{\text{TRST}}$	TDO	TDI	GPT2	PWM7	PWM3	$\overline{\text{IRQ12}}$	AN0	AN3	LNKLED	ACTLED
D	DTIN1	DTIN0	ALLPST	GPT1	VDDX	VDDX	VDD	VDDR	PST2	PST3	SPDLED
E	DDATA3	$\overline{\text{IRQ9}}$	$\overline{\text{IRQ8}}$	VSS	VSS	VDDX	VSS	VDD	PST0	PST1	PHY_RXN
F	DDATA0	DDATA1	DDATA2	VSS	VSS	VSS	VSS	VSS	PHY_VSSRX	PHY_VDDRX	PHY_RXP
G	DTIN2	$\overline{\text{IRQ5}}$	$\overline{\text{IRQ6}}$	JTAG_EN	VDDX	VDDX	VDDX	PHY_VSSA	PHY_VSSTX	PHY_VDDTX	PHY_TXP
H	DTIN3	$\overline{\text{URTS0}}$	$\overline{\text{URTS1}}$	QSPI_DIN	QSPI_CS1	VDDX	TEST	TXLED	RXLED	PHY_VDDA	PHY_TXN
J	SYNCB	$\overline{\text{UCTS0}}$	$\overline{\text{UCTS1}}$	QSPI_DOUT	QSPI_CS2	$\overline{\text{RSTI}}$	XTAL	$\overline{\text{IRQ1}}$	COLLED	DUPLED	PHY_RBIAS
K	SYNCA	URXD0	URXD1	QSPI_CLK	QSPI_CS3	VDDPLL	VSSPLL	$\overline{\text{IRQ2}}$	$\overline{\text{IRQ11}}$	$\overline{\text{URTS2}}$	URXD2
L	$\overline{\text{IRQ10}}$	UTXD0	UTXD1	QSPI_CS0	$\overline{\text{IRQ4}}$	$\overline{\text{RSTO}}$	EXTAL	$\overline{\text{IRQ3}}$	$\overline{\text{IRQ7}}$	$\overline{\text{UCTS2}}$	UTXD2

Figure 4. 121 MAPBGA Pin Assignments

Table 3. Pin Functions by Primary and Alternate Purpose

Pin Group	Primary Function	SecondaryFunction	Tertiary Function	Quaternary Function	Drive Strength/ Control[1]	Wired OR Control	Pull-up/ Pull-down[2]	Pin on 121 MAPBGA	Pin on 112 LQFP	Pin on 80 LQFP
ADC[3]	AN7	—	—	PAN[7]	Low	—	—	A10	88	64
	AN6	—	—	PAN[6]	Low	—	—	B10	87	63
	AN5	—	—	PAN[5]	Low	—	—	A11	86	62
	AN4	—	—	PAN[4]	Low	—	—	B11	85	61
	AN3	—	—	PAN[3]	Low	—	—	C9	89	65
	AN2	—	—	PAN[2]	Low	—	—	B9	90	66
	AN1	—	—	PAN[1]	Low	—	—	A9	91	67
	AN0	—	—	PAN[0]	Low	—	—	C8	92	68
	SYNCA	CANTX[4]	FEC_MDIO	PAS[3]	PDSR[39]	—	—	K1	28	20
	SYNCB	CANRX[4]	FEC_MDC	PAS[2]	PDSR[39]	—	—	J1	27	19
	VDDA	—	—	—	N/A	N/A	—	A8	93	69
	VSSA	—	—	—	N/A	N/A	—	A7	96	72
	VRH	—	—	—	N/A	N/A	—	B8	94	70
	VRL	—	—	—	N/A	N/A	—	B7	95	71
Clock Generation	EXTAL	—	—	—	N/A	N/A	—	L7	48	36
	XTAL	—	—	—	N/A	N/A	—	J7	49	37
	VDDPLL[5]	—	—	—	N/A	N/A	—	K6	45	33
	VSSPLL	—	—	—	N/A	N/A	—	K7	47	35
Debug Data	ALLPST	—	—	—	High	—	—	D3	7	7
	DDATA[3:0]	—	—	PDD[7:4]	High	—	—	E1, F3,F2, F1	12,13,16,17	—
	PST[3:0]	—	—	PDD[3:0]	High	—	—	D10, D9, E10, E9	80,79,78,77	—

Table 3. Pin Functions by Primary and Alternate Purpose (continued)

Pin Group	Primary Function	SecondaryFunction	Tertiary Function	Quaternary Function	Drive Strength/ Control[1]	Wired OR Control	Pull-up/ Pull-down[2]	Pin on 121 MAPBGA	Pin on 112 LQFP	Pin on 80 LQFP
UART 1[3]	$\overline{\text{UCTS1}}$	SYNCA	URXD2	PUB[3]	PDSR[15]	—	—	J3	24	16
	$\overline{\text{URTS1}}$	SYNCB	UTXD2	PUB[2]	PDSR[14]	—	—	H3	23	15
	URXD1	—	FEC_TXD[0]	PUB[1]	PDSR[13]	PWOR[2]	—	K3	32	23
	UTXD1	—	FEC_COL	PUB[0]	PDSR[12]	PWOR[3]	—	L3	33	24
UART 2	$\overline{\text{UCTS2}}$	—	—	PUC[3]	PDSR[27]	—	—	L10	61	—
	$\overline{\text{URTS2}}$	—	—	PUC[2]	PDSR[26]	—	—	K10	60	—
	URXD2	—	—	PUC[1]	PDSR[25]	—	—	K11	62	—
	UTXD2	—	—	PUC[0]	PDSR[24]	—	—	L11	63	—
FlexCAN	SYNCA	CANTX[4]	FEC_MDIO	PAS[3]	PDSR[39]	—	—	—	28	20
	SYNCB	CANRX[4]	FEC_MDC	PAS[2]	PDSR[39]	—	—	—	27	19
VDD[5,11]	VDD	—	—	—	N/A	N/A	—	D7, E8	65,102	45,74
VDDX	VDDX	—	—	—	N/A	N/A	—	D5, D6, E6, G5, G6, G7, H6	14, 43	10, 31
VSS	VSS	—	—	—	N/A	N/A	—	E4, E5, E7,F4, F5, F6, F7, F8	64,101	44,73
VSSX	VSSX	—	—	—	N/A	N/A	—	—	15, 42	11, 30

1 The PDSR and PSSR registers are described in Chapter 14, "General Purpose I/O Module". All programmable signals default to 2mA drive in normal (single-chip) mode.
2 All signals have a pull-up in GPIO mode.
3 The use of an external PHY limits ADC, interrupt, and QSPI functionality. It also disables the UART0/1 and timer pins.
4 The multiplexed CANTX and CANRX signals do not have dedicated pins, but are available as muxed replacements for other signals.
5 The VDD1, VDD2, VDDPLL, and PHY_VDD pins are for decoupling only and should not have power directly applied to them.
6 For primary and GPIO functions only.
7 Only when JTAG mode is enabled.
8 For secondary and GPIO functions only.
9 RSTI has an internal pull-up resistor; however, the use of an external resistor is strongly recommended.
10 For GPIO function. Primary Function has pull-up control within the GPT module.
11 This list for power and ground does not include those dedicated power/ground pins included elsewhere, e.g. in the Ethernet PHY.

1.12 ADC Signals

Table 13 describes the signals of the Analog-to-Digital Converter.

Table 13. ADC Signals

Signal Name	Abbreviation	Function	I/O
Analog Inputs	AN[7:0]	Inputs to the A-to-D converter.	I
Analog Reference	V_{RH}	Reference voltage high and low inputs.	I
	V_{RL}		I
Analog Supply	V_{DDA}	Isolate the ADC circuitry from power supply noise	—
	V_{SSA}		—

1.13 General Purpose Timer Signals

Table 14 describes the General Purpose Timer Signals.

Table 14. GPT Signals

Signal Name	Abbreviation	Function	I/O
General Purpose Timer Input/Output	GPT[3:0]	Inputs to or outputs from the general purppose timer module	I/O

1.14 Pulse Width Modulator Signals

Table 15 describes the PWM signals.

Table 15. PWM Signals

Signal Name	Abbreviation	Function	I/O
PWM Output Channels	PWM[7:0]	Pulse width modulated output for PWM channels	O

1.15 Debug Support Signals

These signals are used as the interface to the on-chip JTAG controller and also to interface to the BDM logic.

Table 16. Debug Support Signals

Signal Name	Abbreviation	Function	I/O
JTAG Enable	JTAG_EN	Select between debug module and JTAG signals at reset	I
Test Reset	$\overline{TRST}$	This active-low signal is used to initialize the JTAG logic asynchronously.	I
Test Clock	TCLK	Used to synchronize the JTAG logic.	I
Test Mode Select	TMS	Used to sequence the JTAG state machine. TMS is sampled on the rising edge of TCLK.	I
Test Data Input	TDI	Serial input for test instructions and data. TDI is sampled on the rising edge of TCLK.	I

Table 16. Debug Support Signals (continued)

Signal Name	Abbreviation	Function	I/O
Test Data Output	TDO	Serial output for test instructions and data. TDO is tri-stateable and is actively driven in the shift-IR and shift-DR controller states. TDO changes on the falling edge of TCLK.	O
Development Serial Clock	DSCLK	Development Serial Clock. Internally synchronized input. (The logic level on DSCLK is validated if it has the same value on two consecutive rising bus clock edges.) Clocks the serial communication port to the debug module during packet transfers. Maximum frequency is PSTCLK/5. At the synchronized rising edge of DSCLK, the data input on DSI is sampled and DSO changes state.	I
Breakpoint	$\overline{\text{BKPT}}$	Breakpoint. Input used to request a manual breakpoint. Assertion of $\overline{\text{BKPT}}$ puts the processor into a halted state after the current instruction completes. Halt status is reflected on processor status signals (PST[3:0]) as the value 0xF. If CSR[BKD] is set (disabling normal $\overline{\text{BKPT}}$ functionality), asserting $\overline{\text{BKPT}}$ generates a debug interrupt exception in the processor.	I
Development Serial Input	DSI	Development Serial Input. Internally synchronized input that provides data input for the serial communication port to the debug module after the DSCLK has been seen as high (logic 1).	I
Development Serial Output	DSO	Development Serial Output. Provides serial output communication for debug module responses. DSO is registered internally. The output is delayed from the validation of DSCLK high.	O
Debug Data	DDATA[3:0]	Display captured processor data and breakpoint status. The CLKOUT signal can be used by the development system to know when to sample DDATA[3:0].	O
Processor Status Clock	PSTCLK	Processor Status Clock. Delayed version of the processor clock. Its rising edge appears in the center of valid PST and DDATA output. PSTCLK indicates when the development system should sample PST and DDATA values. If real-time trace is not used, setting CSR[PCD] keeps PSTCLK, PST, and DDATA outputs from toggling without disabling triggers. Non-quiescent operation can be re-enabled by clearing CSR[PCD], although the external development systems must resynchronize with the PST and DDATA outputs. PSTCLK starts clocking only when the first non-zero PST value (0xC, 0xD, or 0xF) occurs during system reset exception processing.	O
Processor Status Outputs	PST[3:0]	Indicate core status. Debug mode timing is synchronous with the processor clock; status is unrelated to the current bus transfer. The CLKOUT signal can be used by the development system to know when to sample PST[3:0].	O
All Processor Status Outputs	ALLPST	Logical AND of PST[3:0]	O

1.16 EzPort Signal Descriptions

Table 17 contains a list of EzPort external signals

Table 17. EzPort Signal Descriptions

Signal Name	Abbreviation	Function	I/O
EzPort Clock	EZPCK	Shift clock for EzPort transfers	I
EzPort Chip Select	EZPCS	Chip select for signalling the start and end of serial transfers	I
EzPort Serial Data In	EZPD	EZPD is sampled on the rising edge of EZPCK	I
EzPort Serial Data Out	EZPQ	EZPQ transitions on the falling edge of EZPCK	O

1.17 Power and Ground Pins

The pins described in Table 18 provide system power and ground to the chip. Multiple pins are provided for adequate current capability. All power supply pins must have adequate bypass capacitance for high-frequency noise suppression.

Table 18. Power and Ground Pins

Signal Name	Abbreviation	Function	I/O
PLL Analog Supply	VDDPLL, VSSPLL	Dedicated power supply signals to isolate the sensitive PLL analog circuitry from the normal levels of noise present on the digital power supply.	I
Positive Supply	VDD	These pins supply positive power to the core logic.	I
Ground	VSS	This pin is the negative supply (ground) to the chip.	—

Some of the V_{DD} and V_{SS} pins on the device are only to be used for noise bypass. Figure 5 shows a typical connection diagram. Pay particular attention to those pins which show only capacitor connections. Do not connect power supply voltage directly to these pins.

2.6 Reset Timing

Table 27. Reset and Configuration Override Timing

(V_{DD} = 2.7 to 3.6 V, V_{SS} = 0 V, $T_A = T_L$ to T_H)[1]

Num	Characteristic	Symbol	Min	Max	Unit
R1	$\overline{RSTI}$ input valid to CLKOUT high	t_{RVCH}	9	—	ns
R2	CLKOUT high to $\overline{RSTI}$ input invalid	t_{CHRI}	1.5	—	ns
R3	$\overline{RSTI}$ input valid time [2]	t_{RIVT}	5	—	t_{CYC}
R4	CLKOUT high to $\overline{RSTO}$ valid	t_{CHROV}	—	10	ns

[1] All AC timing is shown with respect to 50% V_{DD} levels unless otherwise noted.

[2] During low power STOP, the synchronizers for the $\overline{RSTI}$ input are bypassed and $\overline{RSTI}$ is asserted asynchronously to the system. Therefore, $\overline{RSTI}$ must be held a minimum of 100ns.

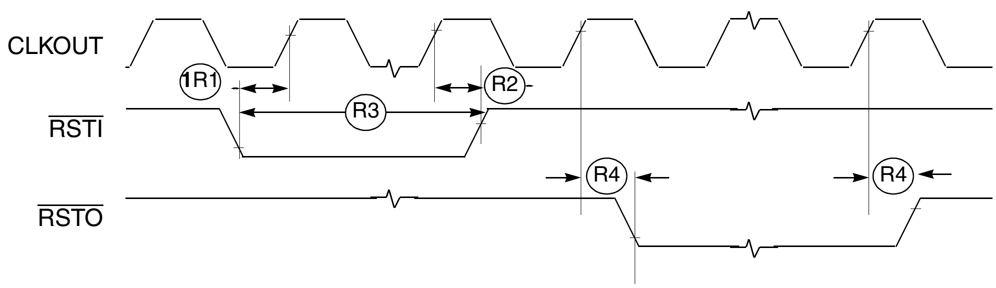


Figure 7. $\overline{RSTI}$ and Configuration Override Timing

2.7 I²C Input/Output Timing Specifications

Table 28 lists specifications for the I²C input timing parameters shown in Figure 8.

Table 28. I²C Input Timing Specifications between I2C_SCL and I2C_SDA

Num	Characteristic	Min	Max	Units
I1	Start condition hold time	$2 \times t_{CYC}$	—	ns
I2	Clock low period	$8 \times t_{CYC}$	—	ns
I3	SCL/SDA rise time (V_{IL} = 0.5 V to V_{IH} = 2.4 V)	—	1	ms
I4	Data hold time	0	—	ns
I5	SCL/SDA fall time (V_{IH} = 2.4 V to V_{IL} = 0.5 V)	—	1	ms
I6	Clock high time	$4 \times t_{CYC}$	—	ns
I7	Data setup time	0	—	ns
I8	Start condition setup time (for repeated start condition only)	$2 \times t_{CYC}$	—	ns
I9	Stop condition setup time	$2 \times t_{CYC}$	—	ns

Table 29 lists specifications for the I²C output timing parameters shown in Figure 8.

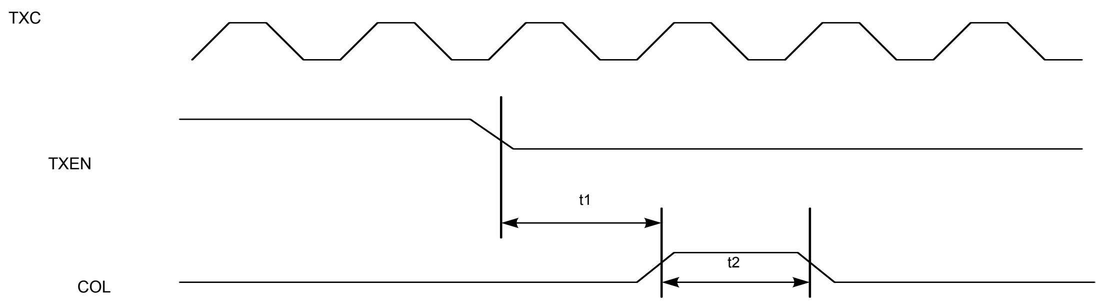


Figure 10. 10BASE-T SQE (Heartbeat) Timing

2.8.3 10BASE-T Jab and Unjab Timing

Table 32 and Figure 11 show the relevant 10BASE-T jab and unjab timing parameters.

Table 32. 10BASE-T Jab and Unjab Timing Parameters

Parameter	Symbol	Min	Typ[1]	Max	Units
Maximum transmit time	t1	—	98	—	ms
Unjab time	t2	—	525	—	ms

[1] Typical values are at 25°C.

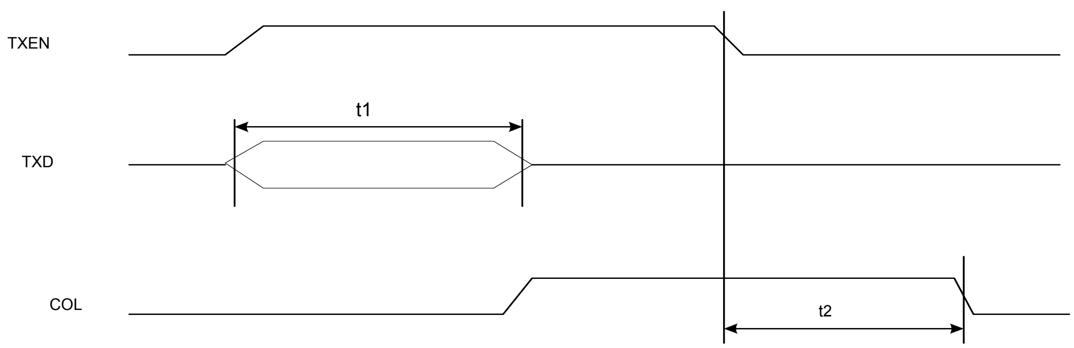
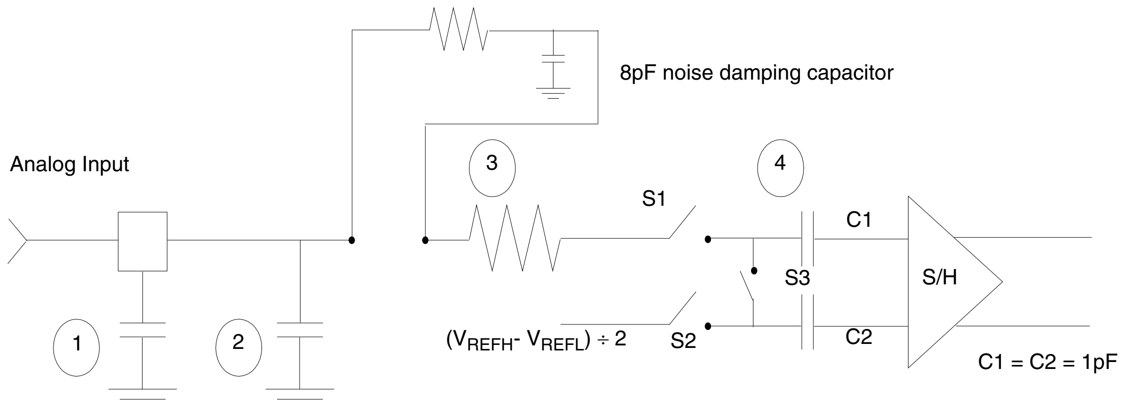


Figure 11. 10BASE-T Jab and Unjab Timing



1 Parasitic capacitance due to package, pin-to-pin and pin-to-package base coupling; 1.8pF
2 Parasitic capacitance due to the chip bond pad, ESD protection devices and signal routing; 2.04pF
3 Equivalent resistance for the channel select mux; 100 ohms
4 Sampling capacitor at the sample and hold circuit. Capacitor C1 is normally disconnected from the input and is only connected to it at sampling time; 1.4pF
5 Equivalent input impedance, when the input is selected = $\frac{1}{\text{ADC CLOCK RATE} \times (1.4 \times 10^{-12})}$

Figure 12. Equivalent Circuit for A/D Loading

2.10 DMA Timers Timing Specifications

Table 36 lists timer module AC timings.

Table 36. Timer Module AC Timing Specifications

Name	Characteristic[1]	Min	Max	Unit
T1	DTIN0 / DTIN1 / DTIN2 / DTIN3 cycle time	$3 \times t_{CYC}$	—	ns
T2	DTIN0 / DTIN1 / DTIN2 / DTIN3 pulse width	$1 \times t_{CYC}$	—	ns

1 All timing references to CLKOUT are given to its rising edge.

2.11 EzPort Electrical Specifications

Table 37. EzPort Electrical Specifications

Name	Characteristic	Min	Max	Unit
EP1	EPCK frequency of operation (all commands except READ)	—	f_{sys} / 2	MHz
EP1a	EPCK frequency of operation (READ command)	—	f_{sys} / 8	MHz
EP2	EPCS_b negation to next EPCS_b assertion	$2 \times T_{cyc}$	—	ns
EP3	EPCS_B input valid to EPCK high (setup)	5	—	ns
EP4	EPCK high to EPCS_B input invalid (hold)	5	—	ns
EP5	EPD input valid to EPCK high (setup)	2	—	ns
EP6	EPCK high to EPD input invalid (hold)	5	—	ns

2.13 JTAG and Boundary Scan Timing

Table 39. JTAG and Boundary Scan Timing

Num	Characteristics[1]	Symbol	Min	Max	Unit
J1	TCLK frequency of operation	f_{JCYC}	DC	1/4	$f_{sys/2}$
J2	TCLK cycle period	t_{JCYC}	$4 \times t_{CYC}$	—	ns
J3	TCLK clock pulse width	t_{JCW}	26	—	ns
J4	TCLK rise and fall times	t_{JCRF}	0	3	ns
J5	Boundary scan input data setup time to TCLK rise	t_{BSDST}	4	—	ns
J6	Boundary scan input data hold time after TCLK rise	t_{BSDHT}	26	—	ns
J7	TCLK low to boundary scan output data valid	t_{BSDV}	0	33	ns
J8	TCLK low to boundary scan output high Z	t_{BSDZ}	0	33	ns
J9	TMS, TDI input data setup time to TCLK rise	t_{TAPBST}	4	—	ns
J10	TMS, TDI input data hold time after TCLK rise	t_{TAPBHT}	10	—	ns
J11	TCLK low to TDO data valid	t_{TDODV}	0	26	ns
J12	TCLK low to TDO high Z	t_{TDODZ}	0	8	ns
J13	$\overline{\text{TRST}}$ assert time	t_{TRSTAT}	100	—	ns
J14	$\overline{\text{TRST}}$ setup time (negation) to TCLK high	t_{TRSTST}	10	—	ns

[1] JTAG_EN is expected to be a static signal. Hence, it is not associated with any timing.

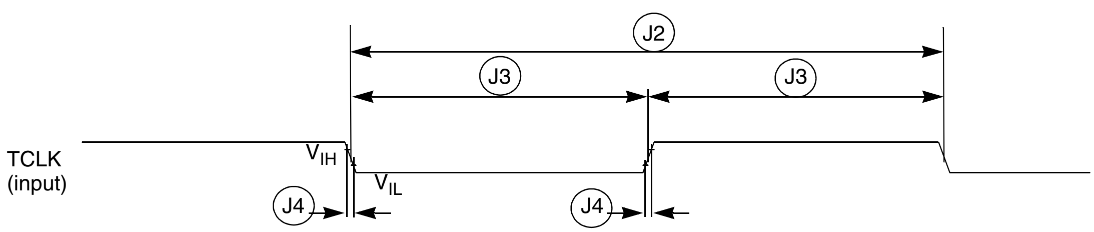


Figure 14. Test Clock Input Timing

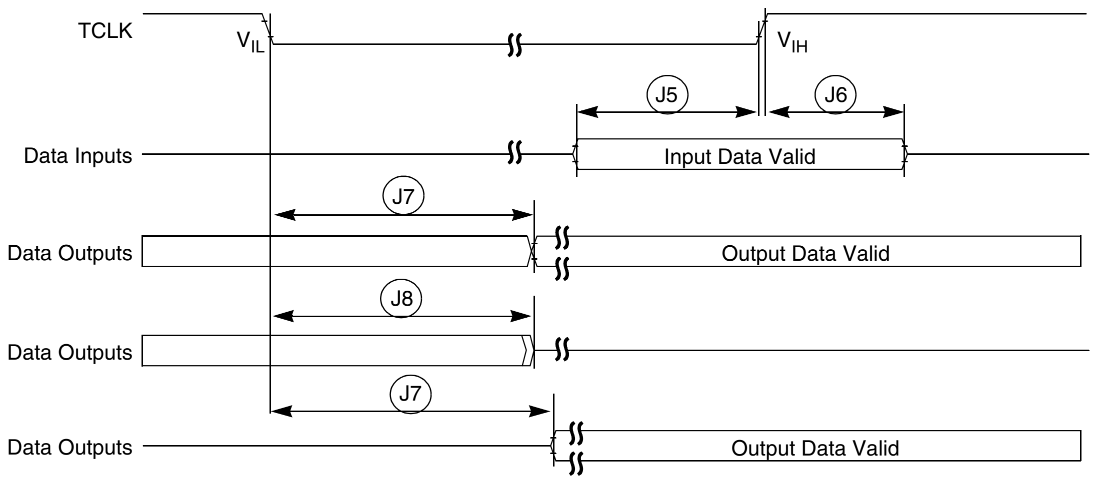


Figure 15. Boundary Scan (JTAG) Timing

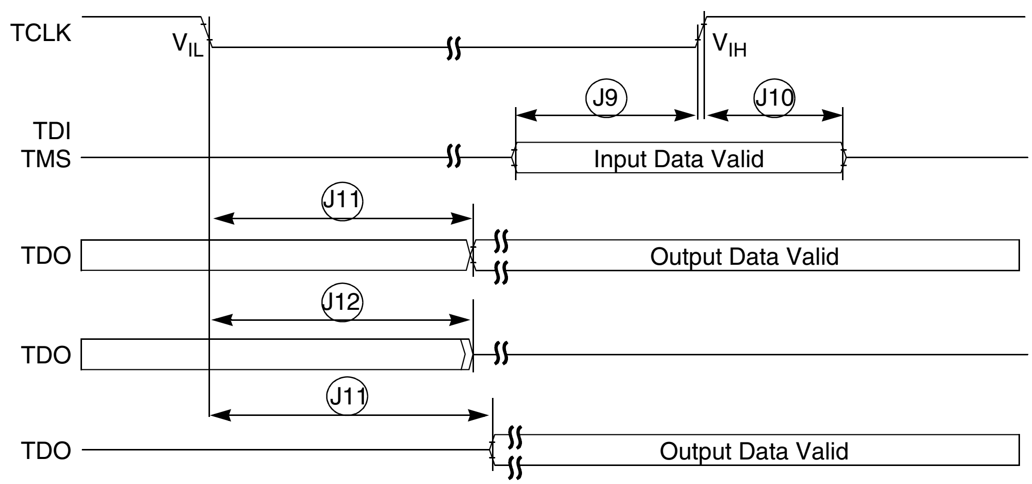


Figure 16. Test Access Port Timing

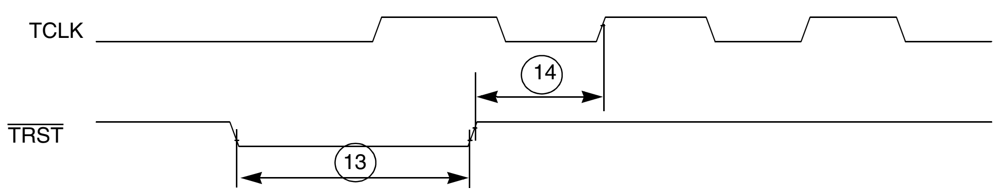


Figure 17. $\overline{\text{TRST}}$ Timing

2.14 Debug AC Timing Specifications

Table 40 lists specifications for the debug AC timing parameters shown in Figure 19.

Table 40. Debug AC Timing Specification

Num	Characteristic	60 MHz		Units
		Min	Max	
D1	PST, DDATA to CLKOUT setup	4	—	ns
D2	CLKOUT to PST, DDATA hold	1.5	—	ns
D3	DSI-to-DSCLK setup	$1 \times t_{CYC}$	—	ns
D4 [1]	DSCLK-to-DSO hold	$4 \times t_{CYC}$	—	ns
D5	DSCLK cycle time	$5 \times t_{CYC}$	—	ns
D6	$\overline{\text{BKPT}}$ input data setup time to CLKOUT Rise	4	—	ns
D7	$\overline{\text{BKPT}}$ input data hold time to CLKOUT Rise	1.5	—	ns
D8	CLKOUT high to $\overline{\text{BKPT}}$ high Z	0.0	10.0	ns

[1] DSCLK and DSI are synchronized internally. D4 is measured from the synchronized DSCLK input relative to the rising edge of CLKOUT.

Figure 18 shows real-time trace timing for the values in Table 40.

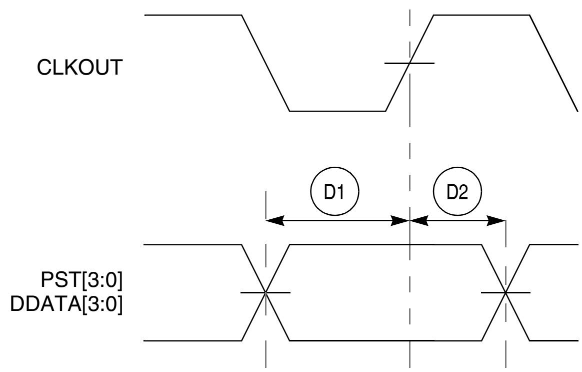


Figure 18. Real-Time Trace AC Timing

Figure 19 shows BDM serial port AC timing for the values in Table 40.

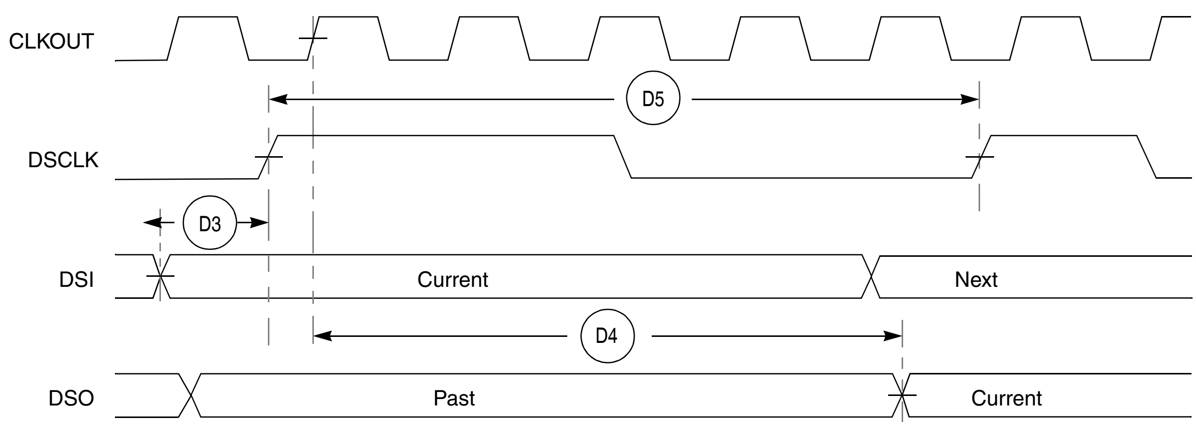
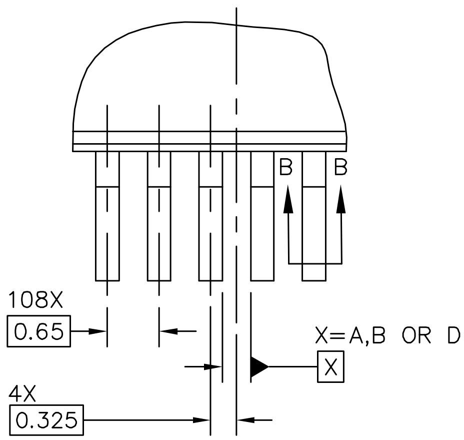
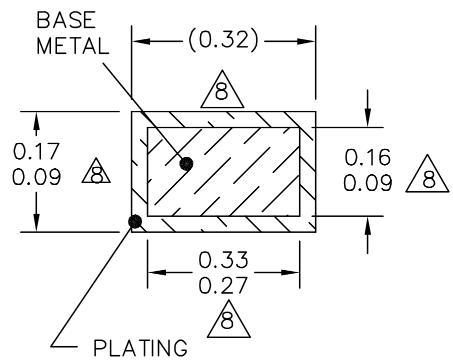


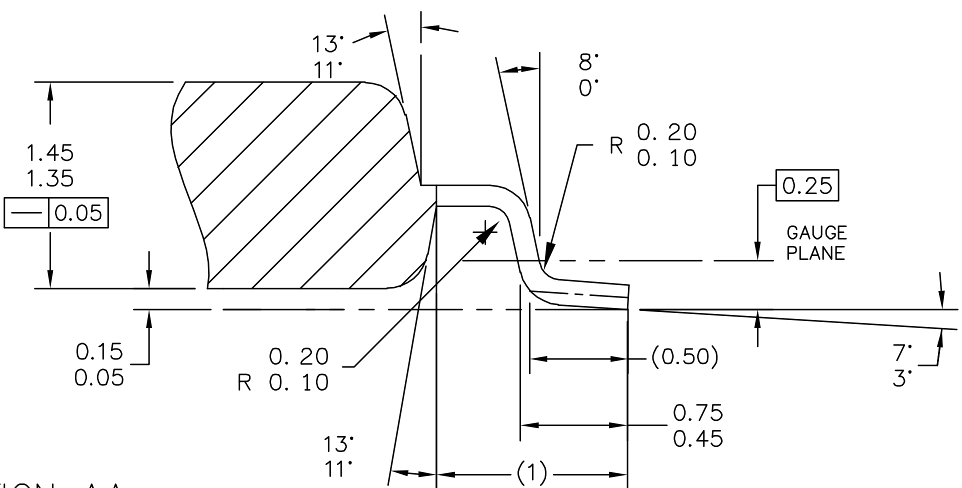
Figure 19. BDM Serial Port AC Timing



VIEW Y



SECTION B–B



SECTION AA

	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 112LD LQFP 20 X 20 X 1. 4 0. 65 PITCH	DOCUMENT NO: 98ASS23330W	REV: E
	CASE NUMBER: 987–02	25 MAY 2005
	STANDARD: JEDEC MS–026 BFA	

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: PBGA, LOW PROFILE, 121 I/O, 12 X 12 PKG, 1 MM PITCH (MAP)	DOCUMENT NO: 98ARE10645D	REV: 0
	CASE NUMBER: 1817-01	15 NOV 2005
	STANDARD: NON-JEDEC	